

ABSTRACT

A temporary protective film for semiconductor encapsulation molding, including a support film and an adhesive layer, the temporary protective film for semiconductor encapsulation molding used for temporarily protecting a surface of a lead frame on a side opposite to a semiconductor element during encapsulation molding of forming a sealing layer that seals the semiconductor element mounted on a die pad of the lead frame. The adhesive layer contains a thermoplastic resin and at least one specific compound selected from the group consisting of sorbitol polyglycidyl ether, polyethylene glycol diglycidyl ether, a glycidyl ether of an aliphatic alcohol having 10 to 20 carbon atoms, glycerol polyglycidyl ether, a polyalkylene glycol ester of a fatty acid having 2 to 30 carbon atoms, a dipentaerythritol ester of a fatty acid having 2 to 20 carbon atoms, polyethylene glycol monoalkyl ether, and polyethylene glycol dialkyl ether.

Fig. 1